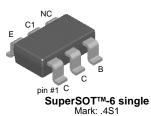


SEMICONDUCTOR®

FMBS5401

PNP General Purpose Amplifier

• This device is designed as a general purpose amplifier and switch for applications requiring high voltage.



PNP Epitaxial Silicon Transistor

Symbol	Parameter	Value	Units	
V _{CEO}	Collector-Emitter Voltage	-150	V	
V _{CBO}	Collector-Base Voltage	-160	V	
V _{EBO}	Emitter-Base Voltage	-5.0	V	
I _C	Collector Current - Continuous	-600	mA	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ 150	°C	

Absolute Maximum Ratings* T_a=25°C unless otherwise noted

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Notes:

These ratings are based on a maximum junction temperature of 150 degrees C.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics Ta=25°C unless otherwise noted

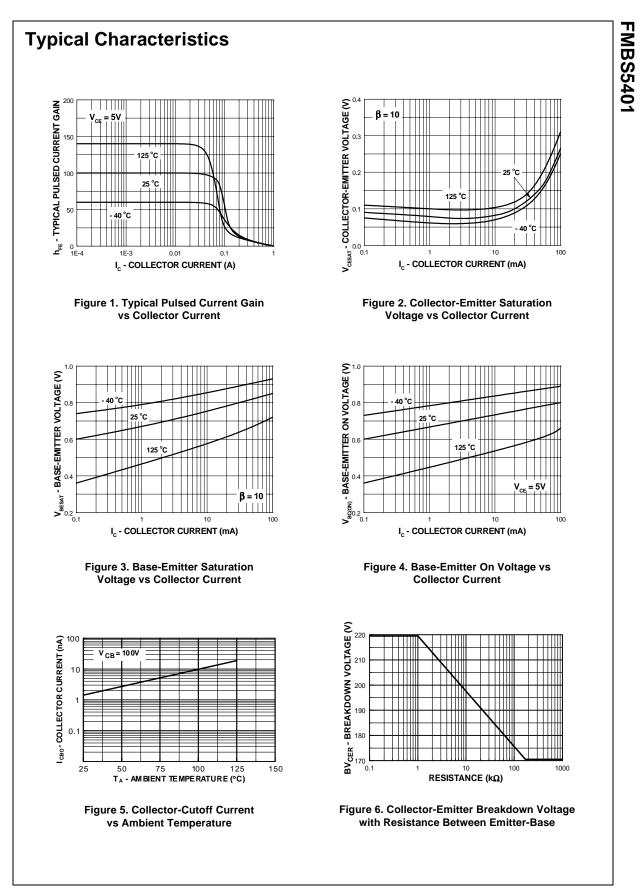
Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charac	teristics				
BV _{CEO}	Collector-Emitter Breakdown Voltage *	$I_{\rm C} = -1.0 {\rm mA}, I_{\rm B} = 0$	-150		V
BV _{CBO}	Collector-Base Breakdown Voltage	$I_{C} = -100 \mu A, I_{E} = 0$	-160		V
BV _{EBO}	Emitter-Base Breakdown Voltage	$I_{E} = -10\mu A, I_{C} = 0$	-5.0		V
I _{CBO}	Collector Cutoff Current	$V_{CB} = -120V, I_E = 0$ $V_{CB} = -120V, I_E = 0, T_a = 100^{\circ}C$		-50 -50	nA μA
I _{EBO}	Emitter Cutoff Current	V _{EB} = -3.0V, I _C =0		-50	nA
On Charac	teristics *				
h _{FE}	DC Current Gain	$I_{C} = -1.0mA, V_{CE} = -5.0V$ $I_{C} = -10mA, V_{CE} = -5.0V$ $I_{C} = -50mA, V_{CE} = -5.0V$	50 60 50	240	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	$I_{C} = -10mA$, $I_{B} = -1.0mA$ $I_{C} = -50mA$, $I_{B} = -5.0mA$		-0.2 -0.5	V V
V _{BE} (sat)	Base-Emitter Saturation Voltage	I _C = -10mA, I _B = -1.0mA I _C = -50mA, I _B = -5.0mA		-1.0 -1.0	V V
Small Sign	al Characterics				
f _T	Current Gain Bandwidth Product	I _C = -10mA, V _{CE} = -10V, f = 100MHz	100	300	MHz
C _{ob}	Output Capacitance	$V_{CB} = -10V, I_E = 0, f = 1MHz$		6.0	pF
N _F	Noise Figure	I_{C} = -250μA, V _{CE} = -5.0V, R _S = 1.0KΩ f = 10Hz to 15.7KHz		8.0	dB

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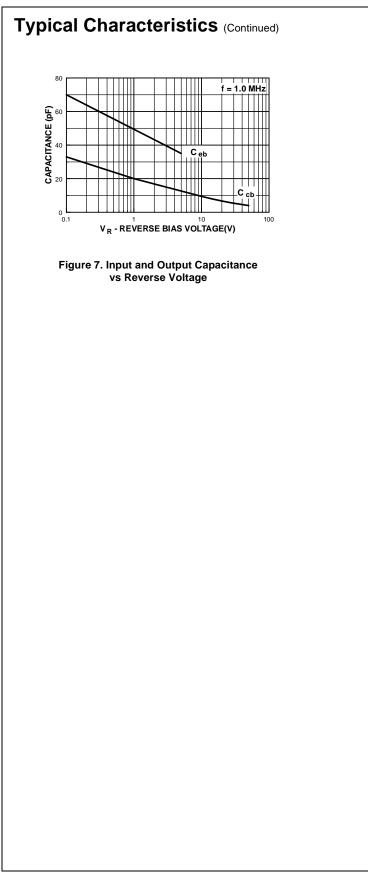
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Total Device Dissipation * 700 mW Thermal Resistance, Junction to Ambient, total 180 °C/W	Total Device Dissipation * 700 mW Thermal Resistance, Junction to Ambient, total 180 °C/W	Total Device Dissipation * 700 mW
Thermal Resistance, Junction to Ambient, total 180 °C/W ounted on a 1 in 2 pad of 2 oz coppe 0 0 0	Thermal Resistance, Junction to Ambient, total 180 °C/W nounted on a 1 in 2 pad of 2 oz coppe 0	Thermal Resistance, Junction to Ambient, total 180 °C/W mounted on a 1 in 2 pad of 2 oz coppe °C/W °C/W
ounted on a 1 in 2 pad of 2 oz coppe	nounted on a 1 in 2 pad of 2 oz coppe	mounted on a 1 in 2 pad of 2 oz coppe

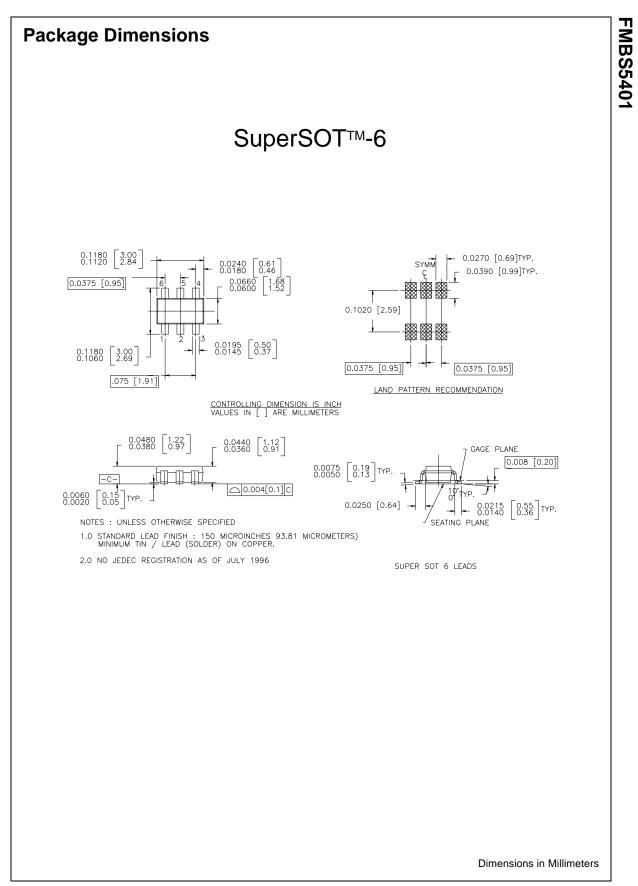
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PRODUCT STATUS DEFINITIONS

Definition of Terms

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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